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(54) Title: CHIP SCALE PACKAGE AND METHOD OF ASSEMBLING THE SAME

(57) Abstract: A method of producing a chip scale package is disclosed. The method includes dicing a wafer into a plurality of chip arrays, each array including two or more integrated circuit chips. The method further includes mounting each array on a substrate and dicing each array, attached to the substrate, into individual chip scale packages, each individual chip scale package including only one integrated circuit chip.

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